

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN THE MATTER OF: KIM et al
SERIAL NO: 10/553,647
FILED: October 14, 2005
TITLE: RESIN COMPOSITION FOR MOLD USED IN FORMING
MICROPATTERN, AND...
GROUP: 4151
CONFIRMATION NO: 5573
EXAMINER: Ryan M. Ochylski

RESPONSE

Commissioner for Patents
P. O. Box 1450
Alexandria, VA 22313-1450

SIR:

This is in response to the outstanding office communication dated December 26, 2008. Applicant respectfully requests that any insufficient fees be deducted from our deposit account 504581.

Please amend the application as follows: